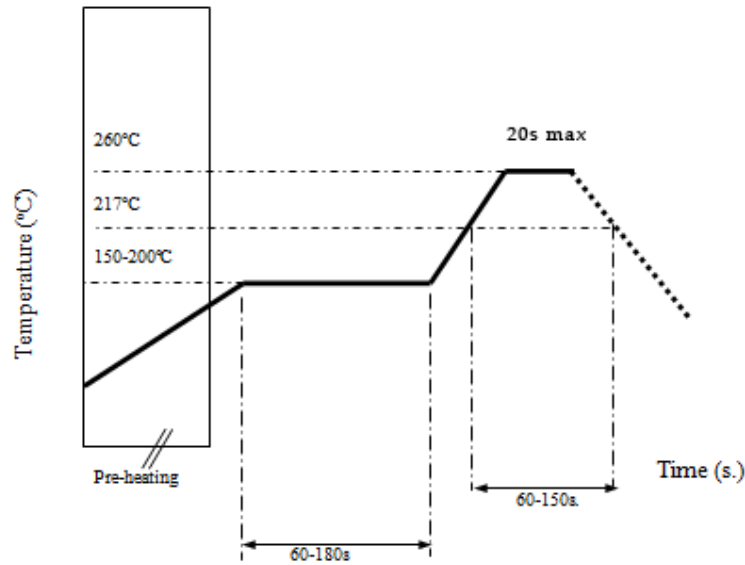


# Integrated Passives Capacitors (IPC) & Antenna Soldering Profile



## Typical Soldering Profile for Lead-free Process: RFCCs

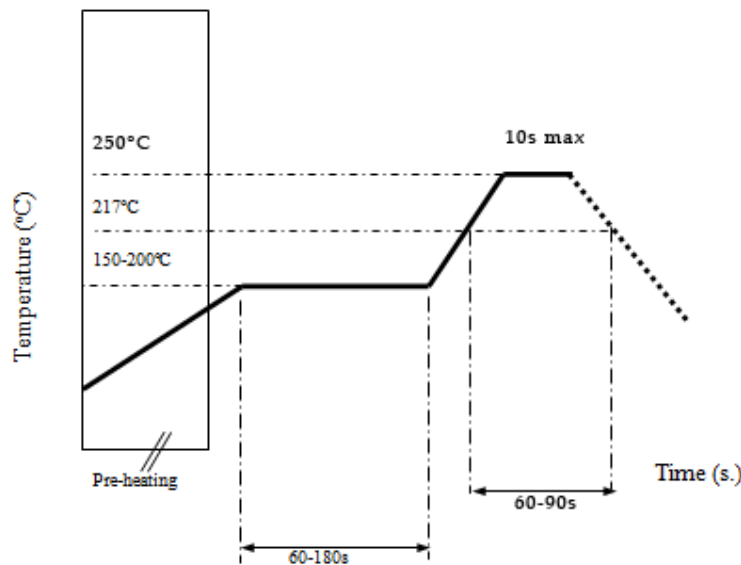
### Reflow Soldering:



<http://www.johansontechnology.com/ipcsoldering-profile>

## Typical Soldering Profile for Solderable Silver (Ag) Terminated Components:\*\*

### Reflow Soldering:



**\*\*Johanson Technology's P/N's with Solderable Silver (Ag/Pt) Terminations  
requiring Vacuum Packaging**

<http://www.johansontechnology.com/silverleads-profile.html>

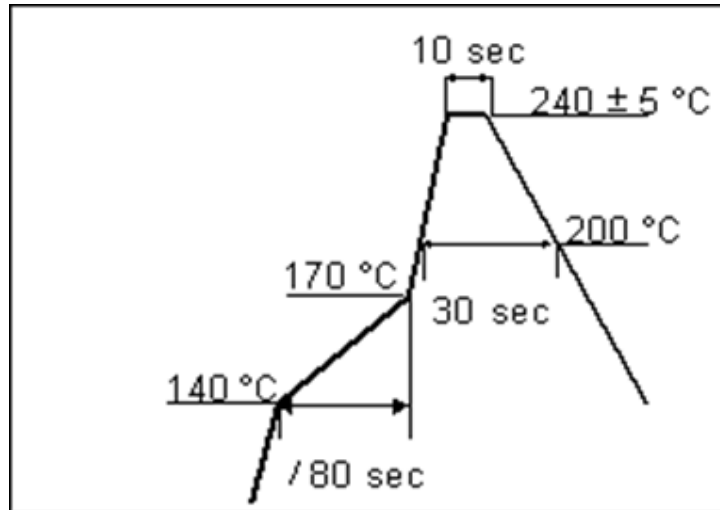
# Integrated Passives Capacitors (IPC) & Antenna Soldering Profile



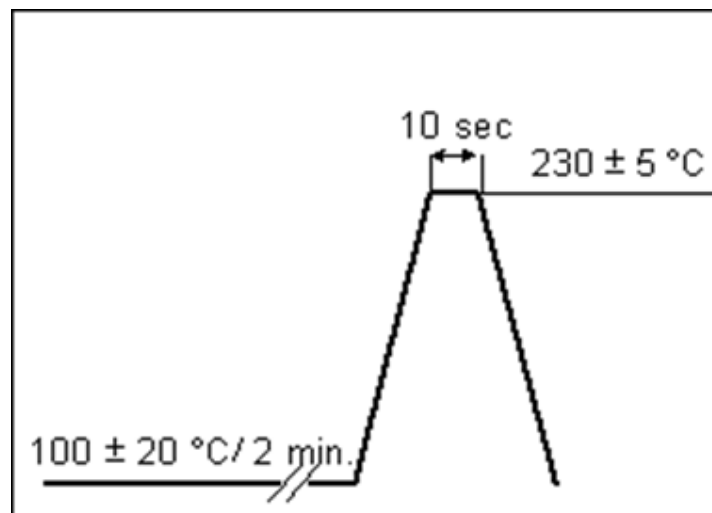
## Typical Soldering Profile for Tin / Lead Terminated

### Components:

#### Flow Soldering



#### Reflow Soldering



## Hand Soldering

Johanson Integrated Passive Components are intended for reflow soldering. When using a soldering iron, care must be used to avoid damaging the terminations and or, in some instances, the ceramic body. Three different issues can occur:

1. Leaching of the termination
2. Delamination of the termination
3. Cracking of the ceramic body

Care must be taken not to overheat or thermal shock the part during the soldering process. An iron having too large of a tip or too high of a temperature significantly increases the probability of compromising the part.

The recommendation for hand soldering our integrated passives is 350°C for 3-5 seconds maximum using a relatively small soldering iron tip.